


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
	2	PRODUCTION	MOLLY Z.	5-05-15

## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE: REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE IS 240 DEGREES CELSIUS.
3. PARTS TO OMIT WILL BE SPECIFIED ON THE BILL OF MATERIALS. LOCATIONS OF OMITTED PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL WHERE SMT PARTS ARE OMITTED.
4. INSTALL SHUNTS AS SHOWN ON ASSY DRAWING.
5. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON FOUR SIDES OF THE BOARD EDGE.
6. DO NOT APPLY ANY KIND OF ASSEMBLY STAMP OR QA STAMP TO ANY BOARD.

APPROVALS		 <b>LINEAR TECHNOLOGY</b> 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	LT			
APP ENG.	MOLLY Z.	<b>TITLE: ASSEMBLY DRAWING</b> SEPIC CONVERTER WITH LOW IQ, POR AND WATCHDOG TIMER		
		SIZE	IC NO.	REV.
		N/A	LT8495EFE DEMO CIRCUIT 2205A	2
SCALE = NONE		FILENAME: DC2205A-2.PCB		SHT 1 OF 1